

ZXMN6A25DN8

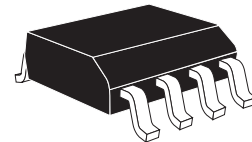
DUAL 60V N-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY

$V_{(BR)DSS} = 60V$; $R_{DS(ON)} = 0.055\Omega$; $I_D = 4.7A$

DESCRIPTION

This new generation of Trench MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



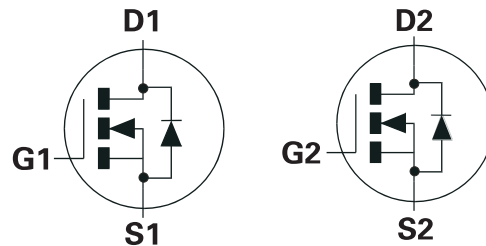
SO8

FEATURES

- Low on-resistance
- Fast switching speed
- Low gate drive
- Low profile SOIC package

APPLICATIONS

- DC - DC Converters
- Power Management Functions
- Motor control



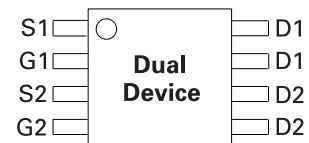
ORDERING INFORMATION

DEVICE	REEL	TAPE WIDTH	QUANTITY PER REEL
ZXMN6A25DN8TA	7"	12mm	500 units
ZXMN6A25DN8TC	13"	12mm	2500 units

DEVICE MARKING

- ZXMN
6A25D

PINOUT



Top view

ZXMN6A25DN8

ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DSS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current @ $V_{GS}=10V$; $T_A=25^\circ C$ ^{(b) (d)}	I_D	4.7	A
@ $V_{GS}=10V$; $T_A=70^\circ C$ ^{(b) (d)}		3.7	A
@ $V_{GS}=10V$; $T_A=25^\circ C$ ^{(a) (d)}		3.6	A
Pulsed Drain Current ^(c)	I_{DM}	22	A
Continuous Source Current (Body Diode) ^(b)	I_S	3.5	A
Pulsed Source Current (Body Diode) ^(c)	I_{SM}	22	A
Power Dissipation at $T_A=25^\circ C$ ^{(a) (d)}	P_D	1.25	W
Linear Derating Factor		10	mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ ^{(a) (e)}	P_D	1.8	W
Linear Derating Factor		14	mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ ^{(b) (d)}	P_D	2.1	W
Linear Derating Factor		17	mW/ $^\circ C$
Operating and Storage Temperature Range	$T_j; T_{stg}$	-55 to +150	$^\circ C$

THERMAL RESISTANCE

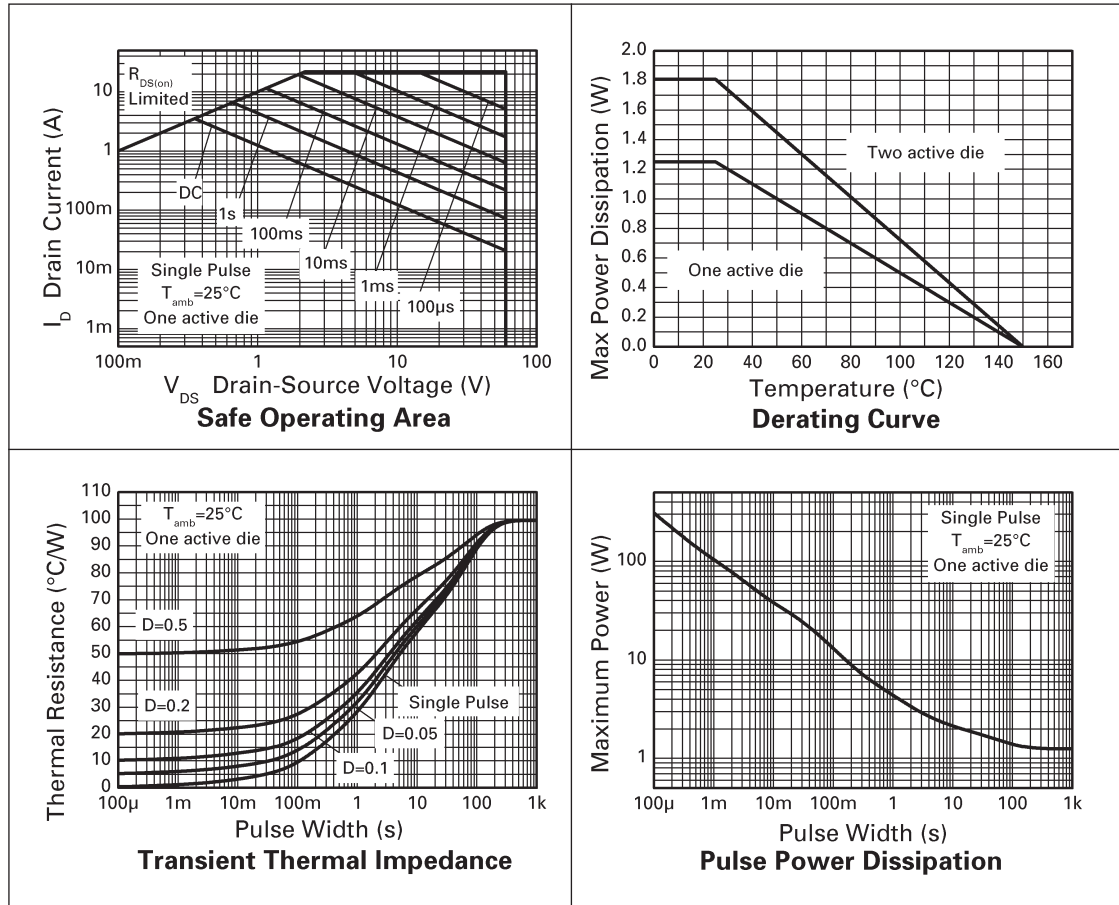
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient ^{(a) (d)}	$R_{\theta JA}$	100	$^\circ C/W$
Junction to Ambient ^{(a) (e)}	$R_{\theta JA}$	70	$^\circ C/W$
Junction to Ambient ^{(b) (d)}	$R_{\theta JA}$	60	$^\circ C/W$

NOTES

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
 (b) For a device surface mounted on FR4 PCB measured at $t \leq 10$ sec.
 (c) Repetitive rating 25mm x 25mm FR4 PCB, $D=0.02$, pulse width=300 μs - pulse width limited by maximum junction temperature.
 (d) For a dual device with one active die.
 (e) For a device with two active die running at equal power.

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TYPICAL CHARACTERISTICS



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ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated).

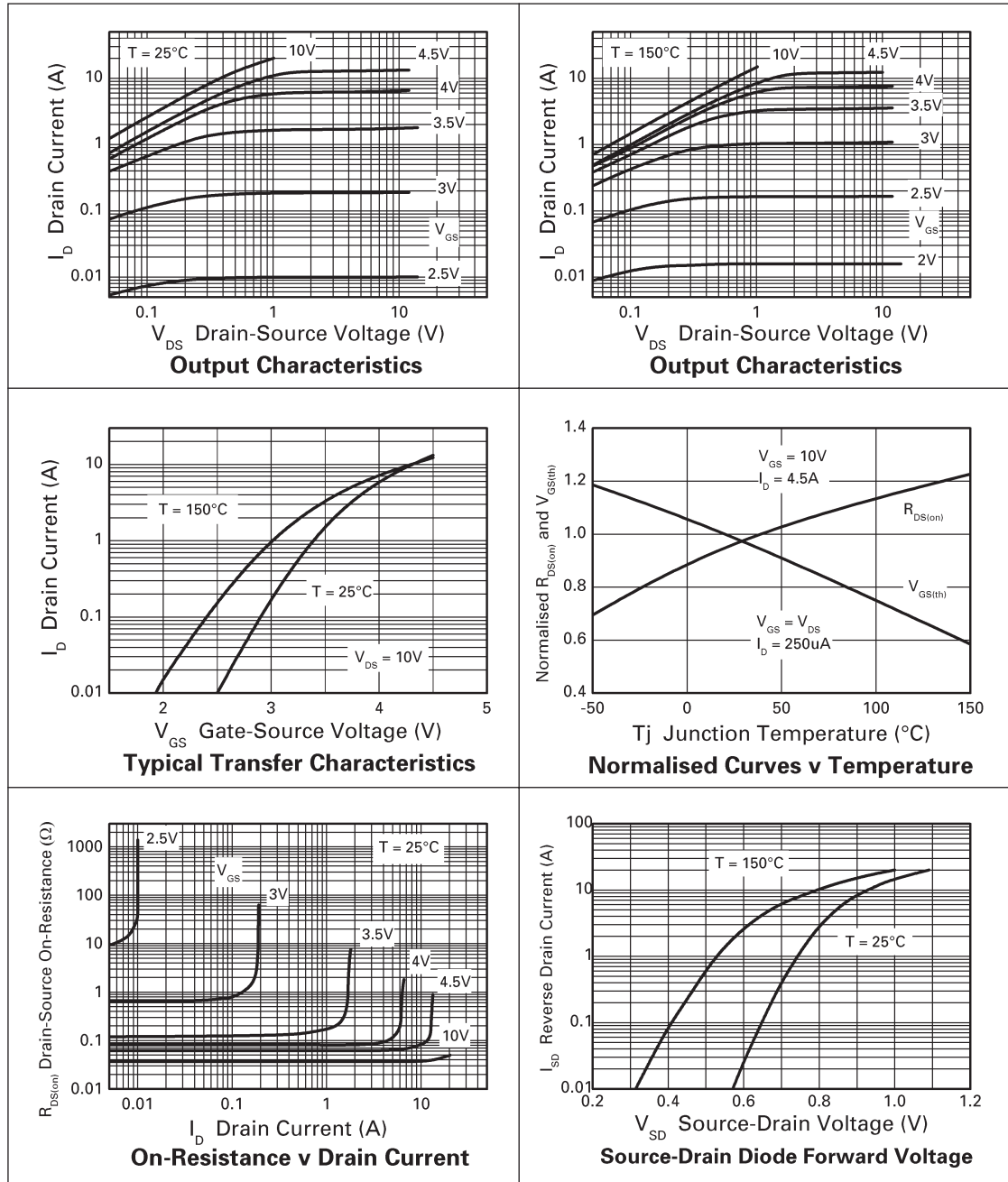
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	60			V	I _D =250μA, V _{GS} =0V
Zero Gate Voltage Drain Current	I _{DSS}			1.0	μA	V _{DS} =60V, V _{GS} =0V
Gate-Body Leakage	I _{GSS}			100	nA	V _{GS} =±20V, V _{DS} =0V
Gate-Source Threshold Voltage	V _{GS(th)}	1.0			V	I _D =250μA, V _{DS} = V _{GS}
Static Drain-Source On-State Resistance ⁽¹⁾	R _{DS(on)}			0.055 0.075	Ω Ω	V _{GS} =10V, I _D =3.6A V _{GS} =4.5V, I _D =3A
Forward Transconductance ^{(1) (3)}	g _{fs}		10.2		S	V _{DS} =15V, I _D =4.5A
DYNAMIC ⁽³⁾						
Input Capacitance	C _{iss}		1063		pF	V _{DS} =30V, V _{GS} =0V, f=1MHz
Output Capacitance	C _{oss}		104		pF	
Reverse Transfer Capacitance	C _{rss}		64		pF	
SWITCHING ^{(2) (3)}						
Turn-On Delay Time	t _{d(on)}		3.8		ns	V _{DD} =30V, I _D =1A R _G =6.0Ω, V _{GS} =10V
Rise Time	t _r		4.0		ns	
Turn-Off Delay Time	t _{d(off)}		26.2		ns	
Fall Time	t _f		10.6		ns	
Gate Charge	Q _g		11.0		nC	V _{DS} =30V, V _{GS} =5V, I _D =4.5A
Total Gate Charge	Q _g		20.4		nC	V _{DS} =30V, V _{GS} =10V, I _D =4.5A
Gate-Source Charge	Q _{gs}		4.1		nC	
Gate-Drain Charge	Q _{gd}		5.1		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage ⁽¹⁾	V _{SD}		0.85	0.95	V	T _J =25°C, I _S =5.5A, V _{GS} =0V
Reverse Recovery Time ⁽³⁾	t _{rr}		22.0		ns	T _J =25°C, I _F =2.2A, di/dt= 100A/μs
Reverse Recovery Charge ⁽³⁾	Q _{rr}		21.4		nC	

NOTES

- (1) Measured under pulsed conditions. Width=300 μs . Duty cycle $\leq 2\%$.
 (2) Switching characteristics are independent of operating junction temperature.
 (3) For design aid only, not subject to production testing.

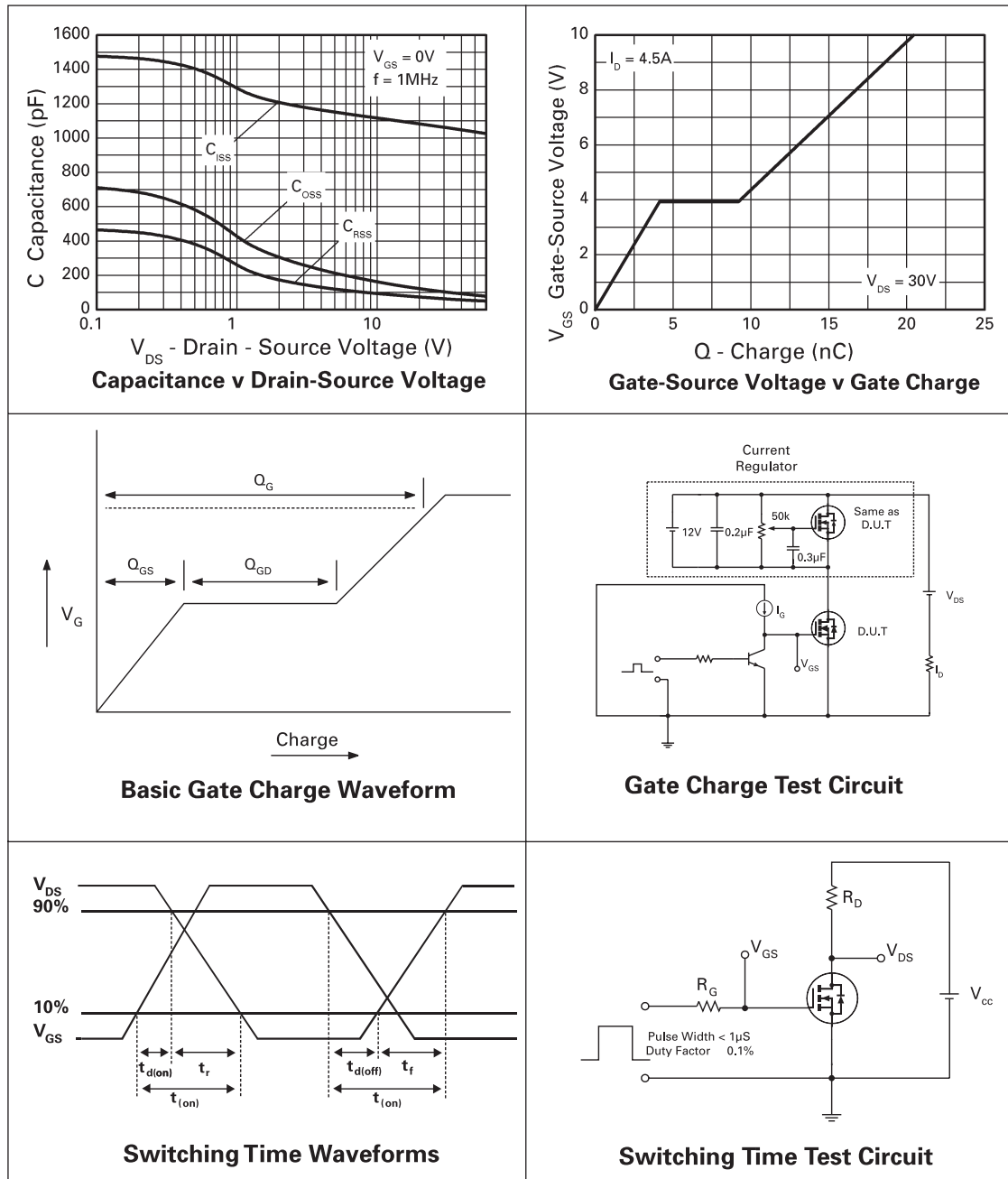
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TYPICAL CHARACTERISTICS



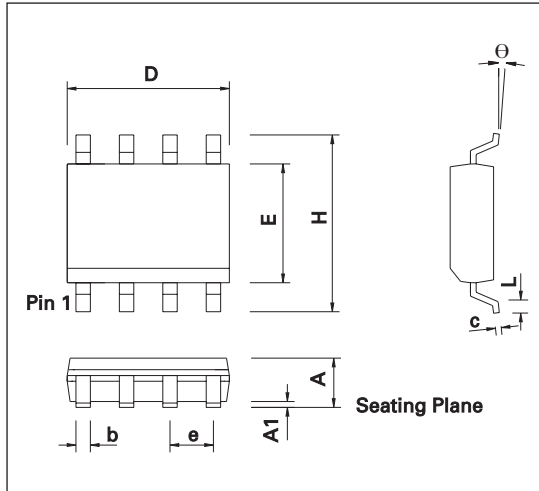
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TYPICAL CHARACTERISTICS



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PACKAGE OUTLINE



CONTROLLING DIMENSIONS ARE IN INCHES
APPROX IN MILLIMETRES

PACKAGE DIMENSIONS

DIM	INCHES		MILLIMETRES	
	MIN	MAX	MIN	MAX
A	0.053	0.069	1.35	1.75
A1	0.004	0.010	0.10	0.25
D	0.189	0.197	4.80	5.00
H	0.228	0.244	5.80	6.20
E	0.150	0.157	3.80	4.00
L	0.016	0.050	0.40	1.27
e	0.050 BSC		1.27 BSC	
b	0.013	0.020	0.33	0.51
c	0.008	0.010	0.19	0.25
Θ	0°	8°	0°	8°
h	0.010	0.020	0.25	0.50

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